

O P E J C 132 AUG 01 2001 PATENT & TRADEMARK OFFICE INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)		Docket Number (Optional) 341.6910USU	Application Number 09/845,549
		Applicant Pasqualoni et al.	
		Filing Date April 30, 2001	Group Art Unit 3723

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	3,170,273	2/23/65	Walsh et al.			
	3,527,028	9/26/67	Donald R. Oswald			RECEIVED
	4,050,954	9/27/77	Jagtar S. Basi			
	4,169,337	10/2/79	Charles C. Payne			AUG 3 2001
	4,304,575	12/8/81	Charles C. Payne			TECHNOLOGY CENTER R3700
	4,462,188	07/31/84	Charles C. Payne			
	5,139,571	08/18/92	Deal et al.			
	5,230,833	07/27/93	Romberger et al.			
	5,246,624	9/21/93	Miller et al.			
	5,314,843	05/24/94	Yu et al.			
	5,340,370	08/23/94	Cadien et al.			

## FOREIGN PATENT DOCUMENTS

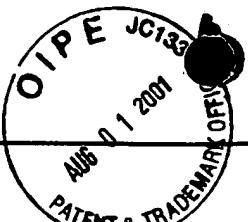
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

	"Chemical-Mechanical Polishing of Copper in Glycerol Based Slurries" (Materials Research Society Symposium Proceedings, 1996), Kumar et al.; no month
	"Chemical-Mechanical Polishing of Copper with Oxide and Polymer Interlevel Dielectrics" (Thin Solid Films, 1995), Gutman et al. no month
	"Stabilization of Alumina Slurry for Chemical-Mechanical Polishing of Copper" (Langmuri, 1996) Lou et al. (no month)

EXAMINER	DATE CONSIDERED
	12/9/01

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.



Sheet 2 of 2

FORM PTO-1449  INFORMATION DISCLOSURE CITATION IN AN APPLICATION  (Use several sheets if necessary)		Docket Number (Optional) 341.6910USU	Application Number 09/845,549
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EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,607,718	3/4/97	Sasaki et al.			
	5,656,097	8/12/97	Olesen et al.			
	5,695,384	12/9/97	Howard R. Beratan			
	5,750,440	5/12/98	Vanell et al.			AUG 3 2001
	5,770,095	6/23/98	Sasaki et al.			TECHNOLOGY CENTER R3700
	5,908,509	6/1/99	Olesen et al.			
	5,954,997	9/21/99	Kaufman et al.			
	5,980,775	11/9/99	Grumbine et al.			
	5,993,685	11/30/99	Currie et al.			
	5,996,595	12/7/99	Olesen et al.			
	6,010,962	1/4/00	Liu et al.			

### FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

### OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

	"Initial Study on Copper MCP Slurry Chemistries" (Thin Solid Films, 1995) Carpio et al.  (no month)
	"Chemical-Mechanical Polishing of Copper for Interconnect Formation" (Microelectronic Engineering, 1997) Stavreva et al. (no month)
	"Development of a 1:1:1 Slurry for Tantalum Layer Polishing" in proceedings of the CMP-MIC conference, February 1999

EXAMINER	DATE CONSIDERED
	12/1/01

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